Amendments to the Claims:

Claims 1 and 18 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) An assembly system for placing a plurality of conductive spheres on a substrate having an upper surface having conductive sites comprising one of recessed sites and level sites with respect to said upper surface, said assembly comprising:

a stencil plate with upper and lower surfaces, and a pattern of a plurality of through-holes said stencil plate configured to place said plurality of conductive spheres in said pattern on a surface of said substrate[[,]] ~~said through holes having a diameter in the range of about two diameters of a conductive sphere to about ten diameters of a conductive sphere~~;

a hopper, said hopper having a bottom opening having a dimension extending across said first pattern for dispensing said spheres into said plurality of through-holes extending across said stencil plate, the bottom opening having width in the range of about two diameters of a conductive sphere to about ten diameters of a conductive sphere, said hopper having a bottom lower surface spaced from an upper surface of the stencil plate a distance in the range of about less that one-half the diameter of a conductive sphere to about less than one-third the diameter of a conductive sphere; and

a positioning apparatus for moving said hopper over said pattern relative said stencil plate to place said spheres into said plurality of through-holes and thereby onto said surface of said substrate.

2. (Previously Presented) The assembly system of claim 1, wherein said spheres drop into and pass downwardly through said through-holes by gravitational force.

3. (Previously Presented) The assembly system of claim 1, wherein said pattern corresponds to a pattern of bond pads on said substrate.

4. (Canceled)

5. (Previously Presented) The assembly system of claim 1, wherein the diameter of said through-holes of said pattern are greater than the diameter of said spheres by up to 1 mm.

6. (Previously Presented) The assembly system of claim 1, wherein said stencil plate is spaced from said substrate to restrain said spheres dropped onto said substrate within said pattern.

7. (Canceled)

8. (Previously Presented) The assembly system of claim 1, wherein said stencil plate is spaced from said substrate to restrain said spheres dropped onto depressed bond pads of said substrate.

9. (Withdrawn) An apparatus for placing conductive spheres on a substrate, comprising:

a stencil plate with a first pattern of a plurality of through-holes, said stencil plate configured to place a plurality of conductive spheres in said first pattern on a surface of a substrate;

a shuttle plate parallel to said stencil plate and proximate thereto, said shuttle plate having a second pattern of through-holes corresponding to said first pattern;

apparatus for moving said shuttle plate from a first position wherein said first and second patterns are axially aligned to a second position wherein said first and second patterns are non-aligned; and

conductive sphere supply means for placing said conductive spheres in said first pattern of through-holes.

10. (Withdrawn) The apparatus of claim 9, wherein said supply means is configured to place said conductive spheres in said first pattern of through-holes when said shuttle plate is in said second position.

11. (Withdrawn) The apparatus of claim 9, wherein said supply means is configured to place said conductive spheres in said first pattern of through-holes when said shuttle plate is in said first position.

12. (Withdrawn) The apparatus of claim 9, wherein said first pattern corresponds to a pattern of bond pads on said substrate.

13. (Withdrawn) The apparatus of claim 9, wherein said sphere supply means comprises a bottomless container with side walls extending downward to proximate said movable shuttle plate, wherein said spheres drop into said through-holes of said second pattern as said shuttle is moved, said side walls encompassing a major portion of said first pattern.

14. (Withdrawn) The apparatus of claim 9, wherein said sphere supply means comprises a container having a bottom with a third pattern of through-holes corresponding to said second pattern.

15. (Withdrawn) The apparatus of claim 14, wherein said third pattern is aligned with said first pattern.

16. (Withdrawn) The apparatus of claim 14, wherein said third pattern is non-aligned with said first pattern.

17. (Withdrawn) The apparatus of claim 9, wherein the diameter of said through-holes of said second pattern are greater than the diameter of said spheres by up to 1 mm.

18. (Currently Amended) An assembly system for positioning a plurality of conductive spheres on a substrate having an upper surface having conductive sites comprising one of recessed sites and level sites with respect to said upper surface, each conductive sphere of said plurality of conductive spheres having a diameter, said assembly comprising:

a stencil plate having an upper surface, having a lower surface, having a pattern of a plurality of through-holes, each through-hole having a diameter, said stencil plate configured to position said plurality of conductive spheres in said pattern on a proximate surface of said substrate[[,]] ~~said through holes having a diameter in the range of about two diameters of a conductive sphere to about ten diameters of a conductive sphere~~;

a hopper, said hopper having a bottom opening with a dimension extending across said pattern for dispensing said spheres into said plurality of through-holes of said pattern of said stencil plate, the bottom opening having width in the range of about two diameters of a conductive sphere to about ten diameters of a conductive sphere, said hopper having a bottom lower surface spaced from an upper surface of the stencil plate a distance in the range of about less that one-half the diameter of a conductive sphere to about less than one-third the diameter of a conductive sphere; and

a positioning apparatus for moving said hopper over said pattern relative of said stencil plate to position said spheres into said plurality of through-holes and thereby onto said proximate surface of said substrate.

19. (Previously Presented) The assembly system of claim 18, wherein said spheres drop into and pass downwardly through said through-holes by gravitational force.

20. (Previously Presented) The assembly system of claim 18, wherein said first pattern corresponds to a pattern of bond pads on said substrate.

21. (Canceled)

22. (Previously Presented) The assembly system of claim 18, wherein the diameters of said through-holes of said first pattern are greater than the diameters of said plurality of spheres by up to 1 mm.

23. (Previously Presented) The assembly system of claim 19, wherein said stencil plate is spaced from said substrate to restrain said spheres dropped onto said substrate within said first pattern.

24. (Canceled)

25. (Previously Presented) The assembly system of claim 20, wherein said stencil plate is spaced from said substrate to restrain said spheres dropped onto depressed bond pads of said substrate.

26. (Withdrawn) An apparatus for positioning conductive spheres on a substrate, each sphere having a diameter, said apparatus comprising:

a stencil plate with a first pattern of a plurality of through-holes, each through-hole having a diameter, said stencil plate configured to position a plurality of conductive spheres in said first pattern on a surface of a substrate;

a shuttle plate parallel to said stencil plate and proximate thereto, said shuttle plate having a second pattern of through-holes corresponding to said first pattern, each through-hole of said second pattern of through-holes having a diameter;

apparatus for moving said shuttle plate from a first position wherein said first and second patterns are substantially aligned to a second position wherein said first and second patterns are non-aligned; and

conductive sphere supply means for positioning said conductive spheres in said first pattern of through-holes.

27. (Withdrawn) The apparatus of claim 26, wherein said sphere supply means is configured to position said conductive spheres in said first pattern of through-holes when said shuttle plate is in said second position.

28. (Withdrawn) The apparatus of claim 26, wherein said supply means is configured to position said conductive spheres in said first pattern of through-holes when said shuttle plate is in said first position.

29. (Withdrawn) The apparatus of claim 26, wherein said first pattern corresponds to a pattern of bond pads on said substrate.

30. (Withdrawn) The apparatus of claim 26, wherein said sphere supply means comprises a bottomless container with side walls extending downwardly to proximate said shuttle plate, wherein said spheres drop into said through-holes of said second pattern as said shuttle plate is moved, said side walls encompassing a major portion of said first pattern.

31. (Withdrawn) The apparatus of claim 26, wherein said sphere supply means comprises a container having a bottom with a third pattern of through-holes corresponding to said second pattern.

32. (Withdrawn) The apparatus of claim 31, wherein said third pattern is aligned with said first pattern.

33. (Withdrawn) The apparatus of claim 31, wherein said third pattern is non-aligned with said first pattern.

34. (Withdrawn) The apparatus of claim 26, wherein the diameters of said through-holes of said second pattern are greater than the diameters of said spheres by up to 1 mm.